

## TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT SILICON GATE CMOS

### 524,288-WORD BY 8-BIT FULL CMOS STATIC RAM

#### DESCRIPTION

The TC55VCM208ASTN is a 4,194,304-bit static random access memory (SRAM) organized as 524,288 words by 8 bits. Fabricated using Toshiba's CMOS Silicon gate process technology, this device operates from a single 2.3 to 3.6 V power supply. Advanced circuit technology provides both high speed and low power at an operating current of 3 mA/MHz and a minimum cycle time of 40 ns. It is automatically placed in low-power mode at 0.7  $\mu$ A standby current (at  $V_{DD} = 3$  V,  $T_a = 25^\circ\text{C}$ , typical) when chip enable ( $\overline{\text{CE1}}$ ) is asserted high or ( $\text{CE2}$ ) is asserted low. There are three control inputs.  $\overline{\text{CE1}}$  and  $\text{CE2}$  are used to select the device and for data retention control, and output enable ( $\overline{\text{OE}}$ ) provides fast memory access. This device is well suited to various microprocessor system applications where high speed, low power and battery backup are required. And, with a guaranteed operating extreme temperature range of  $-40^\circ$  to  $85^\circ\text{C}$ , the TC55VCM208ASTN can be used in environments exhibiting extreme temperature conditions. The TC55VCM208ASTN is available in a plastic 40-pin thin-small outline package (TSOP).

#### FEATURES

- Low-power dissipation  
Operating: 9 mW/MHz (typical)
- Single power supply voltage of 2.3 to 3.6 V
- Power down features using  $\overline{\text{CE1}}$  and  $\text{CE2}$
- Data retention supply voltage of 1.5 to 3.6 V
- Direct TTL compatibility for all inputs and outputs
- Wide operating temperature range of  $-40^\circ$  to  $85^\circ\text{C}$
- Standby Current (maximum):

3.6 V	10 $\mu$ A
3.0 V	5 $\mu$ A

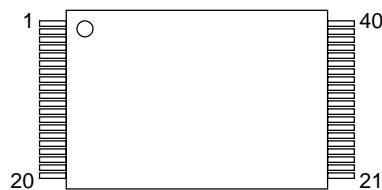
- Access Times:

	TC55VCM208ASTN	
	40	55
Access Time	40 ns	55 ns
$\overline{\text{CE1}}$ Access Time	40 ns	55 ns
$\text{CE2}$ Access Time	40 ns	55 ns
$\overline{\text{OE}}$ Access Time	25 ns	30 ns

- Package:  
TSOP 40-P-1014-0.50 (Weight:0.30 g typ)

#### PIN ASSIGNMENT (TOP VIEW)

##### 40 PIN TSOP



(Normal)

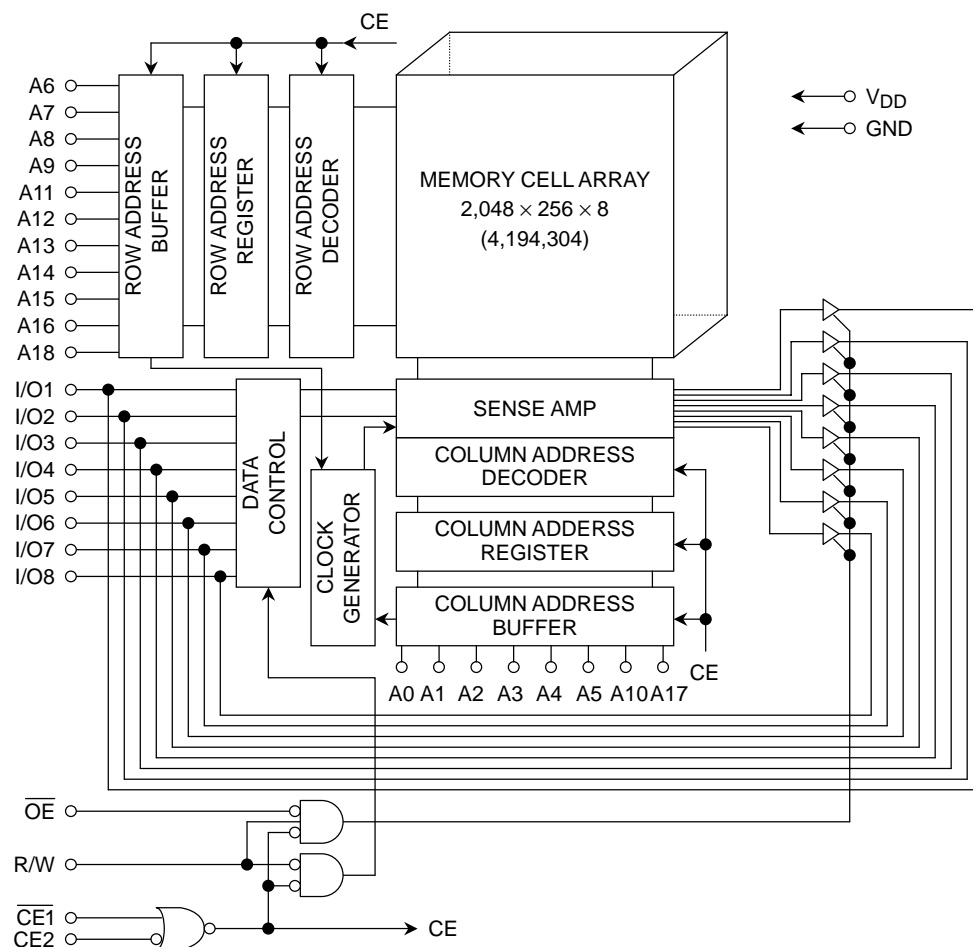
#### PIN NAMES

A0~A18	Address Inputs
$\overline{\text{CE1}}$ , $\text{CE2}$	Chip Enable
R/W	Read/Write Control
$\overline{\text{OE}}$	Output Enable
$\overline{\text{LB}}$ , $\overline{\text{UB}}$	Data Byte Control
I/O1~I/O16	Data Inputs/Outputs
$V_{DD}$	Power
GND	Ground
NC	No Connection
OP*	Option

\*: OP pin must be open or connected to GND.

Pin No.	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
Pin Name	A16	A15	A14	A13	A12	A11	A9	A8	R/W	CE2	OP	NC	A18	A7	A6	A5	A4	A3	A2	A1
Pin No.	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39	40
Pin Name	A0	$\overline{\text{CE1}}$	GND	$\overline{\text{OE}}$	I/O1	I/O2	I/O3	I/O4	NC	$V_{DD}$	$V_{DD}$	I/O5	I/O6	I/O7	I/O8	A10	NC	NC	GND	A17

## BLOCK DIAGRAM



## OPERATING MODE

MODE	$\overline{\text{CE1}}$	CE2	$\overline{\text{OE}}$	R/W	I/O1~I/O8	POWER
Read	L	H	L	H	Output	I <sub>DDO</sub>
Write	L	H	*	L	Input	I <sub>DDO</sub>
Output Deselect	L	H	H	H	High-Z	I <sub>DDO</sub>
Standby	H	*	*	*	High-Z	I <sub>DDS</sub>
	*	L	*	*	High-Z	I <sub>DDS</sub>

\* = don't care  
H = logic high  
L = logic low

## MAXIMUM RATINGS

SYMBOL	RATING	VALUE	UNIT
V <sub>DD</sub>	Power Supply Voltage	−0.3~4.2	V
V <sub>IN</sub>	Input Voltage	−0.3*~4.2	V
V <sub>I/O</sub>	Input/Output Voltage	−0.5~V <sub>DD</sub> + 0.5	V
P <sub>D</sub>	Power Dissipation	0.6	W
T <sub>solder</sub>	Soldering Temperature (10s)	260	°C
T <sub>stg</sub>	Storage Temperature	−55~150	°C
T <sub>opr</sub>	Operating Temperature	−40~85	°C

\*: -2.0 V when measured at a pulse width of 20ns

**DC RECOMMENDED OPERATING CONDITIONS** ( $T_a = -40^\circ$  to  $85^\circ\text{C}$ )

SYMBOL	PARAMETER		MIN	TYP	MAX	UNIT
$V_{DD}$	Power Supply Voltage		2.3	—	3.6	V
$V_{IH}$	Input High Voltage	$V_{DD} = 2.3\text{ V} \sim 2.7\text{ V}$	2.0	—	$V_{DD} + 0.3$	V
		$V_{DD} = 2.7\text{ V} \sim 3.6\text{ V}$	2.2			
$V_{IL}$	Input Low Voltage		$-0.3^*$	—	$V_{DD} \times 0.24$	V
$V_{DH}$	Data Retention Supply Voltage		1.5	—	3.6	V

\*:  $-2.0\text{ V}$  when measured at a pulse width of 20ns

**DC CHARACTERISTICS** ( $T_a = -40^\circ$  to  $85^\circ\text{C}$ ,  $V_{DD} = 2.3$  to  $3.6\text{ V}$ )

SYMBOL	PARAMETER	TEST CONDITION			MIN	TYP	MAX	UNIT
I <sub>IL</sub>	Input Leakage Current	V <sub>IN</sub> = 0 V~V <sub>DD</sub>			—	—	±1.0	μA
I <sub>OH</sub>	Output High Current	V <sub>OH</sub> = V <sub>DD</sub> – 0.5 V			–0.5	—	—	mA
I <sub>OL</sub>	Output Low Current	V <sub>OL</sub> = 0.4 V			2.1	—	—	mA
I <sub>LO</sub>	Output Leakage Current	CE1 = V <sub>IH</sub> or CE2 = V <sub>IL</sub> or R/W = V <sub>IL</sub> or OE = V <sub>IH</sub> , V <sub>OUT</sub> = 0 V~V <sub>DD</sub>			—	—	±1.0	μA
I <sub>DDO1</sub>	Operating Current	CE1 = V <sub>IL</sub> and CE2 = V <sub>IH</sub> and R/W = V <sub>IH</sub> , I <sub>OUT</sub> = 0 mA, Other Input = V <sub>IH</sub> /V <sub>IL</sub>	t <sub>cycle</sub>	MIN	—	—	35	mA
				1 μs	—	—	8	
I <sub>DDO2</sub>		CE1 = 0.2 V and CE2 = V <sub>DD</sub> – 0.2 V and R/W = V <sub>DD</sub> – 0.2 V, I <sub>OUT</sub> = 0 mA, Other Input = V <sub>DD</sub> – 0.2 V/0.2 V		MIN	—	—	30	mA
				1 μs	—	—	3	
I <sub>DDS1</sub>	Standby Current	CE1 = V <sub>IH</sub> or CE2 = V <sub>IL</sub>			—	—	1	mA
I <sub>DDS2</sub>		CE1 = V <sub>DD</sub> – 0.2 V or CE2 = 0.2 V	V <sub>DD</sub> = 3.3V± 0.3 V	Ta = –40~85°C	—	—	10	μA
			V <sub>DD</sub> =3.0 V	Ta = 25°C	—	0.7	—	
				Ta = –40~40°C	—	—	2	
			Ta = –40~85°C	—	—	5		

**CAPACITANCE** ( $T_a = 25^\circ\text{C}$ ,  $f = 1\text{ MHz}$ )

SYMBOL	PARAMETER	TEST CONDITION	MAX	UNIT
$C_{IN}$	Input Capacitance	$V_{IN} = \text{GND}$	10	pF
$C_{OUT}$	Output Capacitance	$V_{OUT} = \text{GND}$	10	pF

Note: This parameter is periodically sampled and is not 100% tested.

**AC CHARACTERISTICS AND OPERATING CONDITIONS**

 (Ta = -40° to 85°C, V<sub>DD</sub> = 2.7 to 3.6 V)

**READ CYCLE**

SYMBOL	PARAMETER	TC55VCM208ASTN				UNIT
		40		55		
		MIN	MAX	MIN	MAX	
t <sub>RC</sub>	Read Cycle Time	40	—	55	—	ns
t <sub>ACC</sub>	Address Access Time	—	40	—	55	
t <sub>CO1</sub>	Chip Enable( $\overline{CE1}$ ) Access Time	—	40	—	55	
t <sub>CO2</sub>	Chip Enable(CE2) Access Time	—	40	—	55	
t <sub>OE</sub>	Output Enable Access Time	—	25	—	30	
t <sub>COE</sub>	Chip Enable Low to Output Active	5	—	5	—	
t <sub>OOE</sub>	Output Enable Low to Output Active	0	—	0	—	
t <sub>OD</sub>	Chip Enable High to Output High-Z	—	20	—	25	
t <sub>ODO</sub>	Output Enable High to Output High-Z	—	20	—	25	
t <sub>OH</sub>	Output Data Hold Time	10	—	10	—	

**WRITE CYCLE**

SYMBOL	PARAMETER	TC55VCM208ASTN				UNIT
		40		55		
		MIN	MAX	MIN	MAX	
tWC	Write Cycle Time	40	—	55	—	ns
tWP	Write Pulse Width	30	—	40	—	
tCW	Chip Enable to End of Write	35	—	45	—	
tAS	Address Setup Time	0	—	0	—	
tWR	Write Recovery Time	0	—	0	—	
tODW	R/W Low to Output High-Z	—	20	—	25	
tOEW	R/W High to Output Active	0	—	0	—	
tDS	Data Setup Time	20	—	25	—	
tDH	Data Hold Time	0	—	0	—	

Note: t<sub>OD</sub>, t<sub>ODO</sub> and t<sub>ODW</sub> are specified in time when an output becomes high impedance, and are not judged depending on an output voltage level.

## AC CHARACTERISTICS AND OPERATING CONDITIONS

(Ta = -40° to 85°C, V<sub>DD</sub> = 2.3 to 3.6 V)

### READ CYCLE

SYMBOL	PARAMETER	TC55VCM208ASTN				UNIT
		40		55		
		MIN	MAX	MIN	MAX	
t <sub>RC</sub>	Read Cycle Time	55	—	70	—	ns
t <sub>ACC</sub>	Address Access Time	—	55	—	70	
t <sub>CO1</sub>	Chip Enable( $\overline{CE1}$ ) Access Time	—	55	—	70	
t <sub>CO2</sub>	Chip Enable(CE2) Access Time	—	55	—	70	
t <sub>OE</sub>	Output Enable Access Time	—	30	—	35	
t <sub>COE</sub>	Chip Enable Low to Output Active	5	—	5	—	
t <sub>OOE</sub>	Output Enable Low to Output Active	0	—	0	—	
t <sub>OD</sub>	Chip Enable High to Output High-Z	—	25	—	30	
t <sub>ODO</sub>	Output Enable High to Output High-Z	—	25	—	30	
t <sub>OH</sub>	Output Data Hold Time	10	—	10	—	

### WRITE CYCLE

SYMBOL	PARAMETER	TC55VCM208ASTN				UNIT
		40		55		
		MIN	MAX	MIN	MAX	
tWC	Write Cycle Time	55	—	70	—	ns
tWP	Write Pulse Width	40	—	50	—	
tCW	Chip Enable to End of Write	45	—	55	—	
tAS	Address Setup Time	0	—	0	—	
tWR	Write Recovery Time	0	—	0	—	
tODW	R/W Low to Output High-Z	—	25	—	30	
tOEW	R/W High to Output Active	0	—	0	—	
tDS	Data Setup Time	25	—	30	—	
tDH	Data Hold Time	0	—	0	—	

Note: t<sub>OD</sub>, t<sub>ODO</sub> and t<sub>ODW</sub> are specified in time when an output becomes high impedance, and are not judged depending on an output voltage level.

AC TEST CONDITIONS

PARAMETER	TEST CONDITION
Input pulse level	0.2 V, $V_{DD} \times 0.7 \text{ V} + 0.2 \text{ V}$
$t_R$ , $t_F$	1 V / ns (Fig.1)
Timing measurements	$V_{DD} \times 0.5$
Reference level	$V_{DD} \times 0.5$
Output load	30 pF + 1 TTL Gate (Fig.2)

Fig.1 : Input rise and fall time

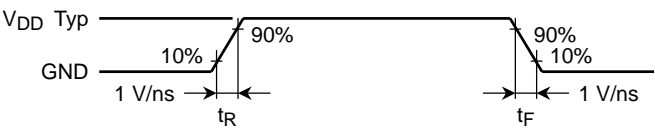
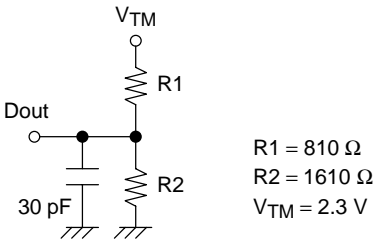
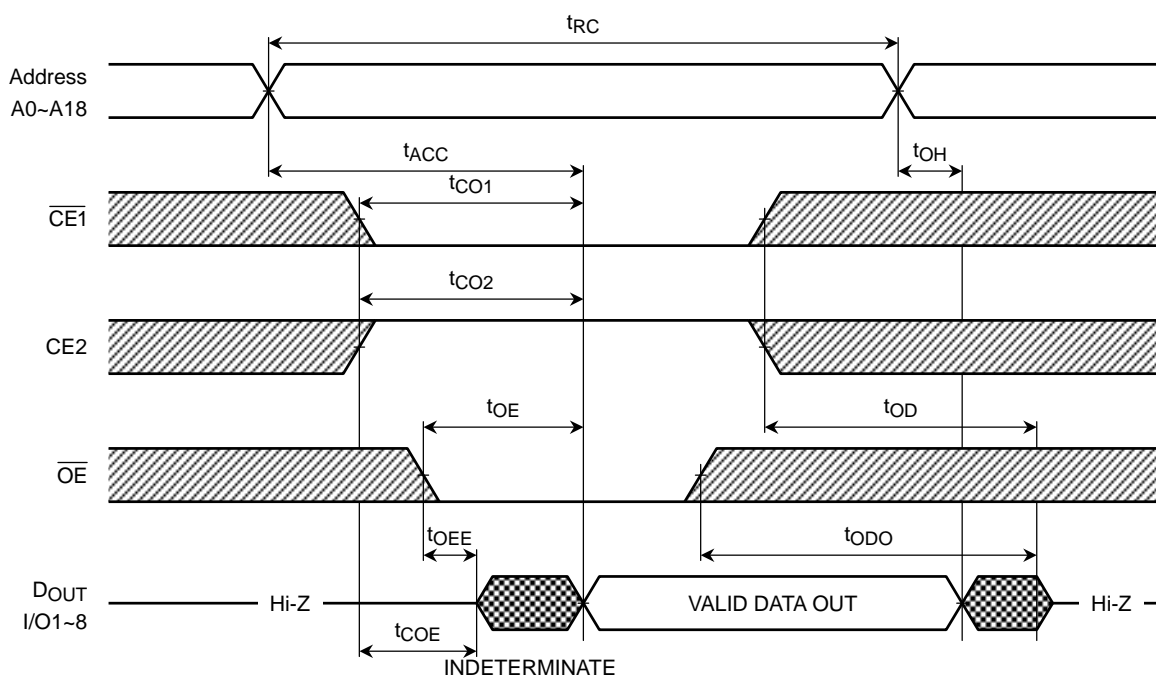


Fig.2 : Output load

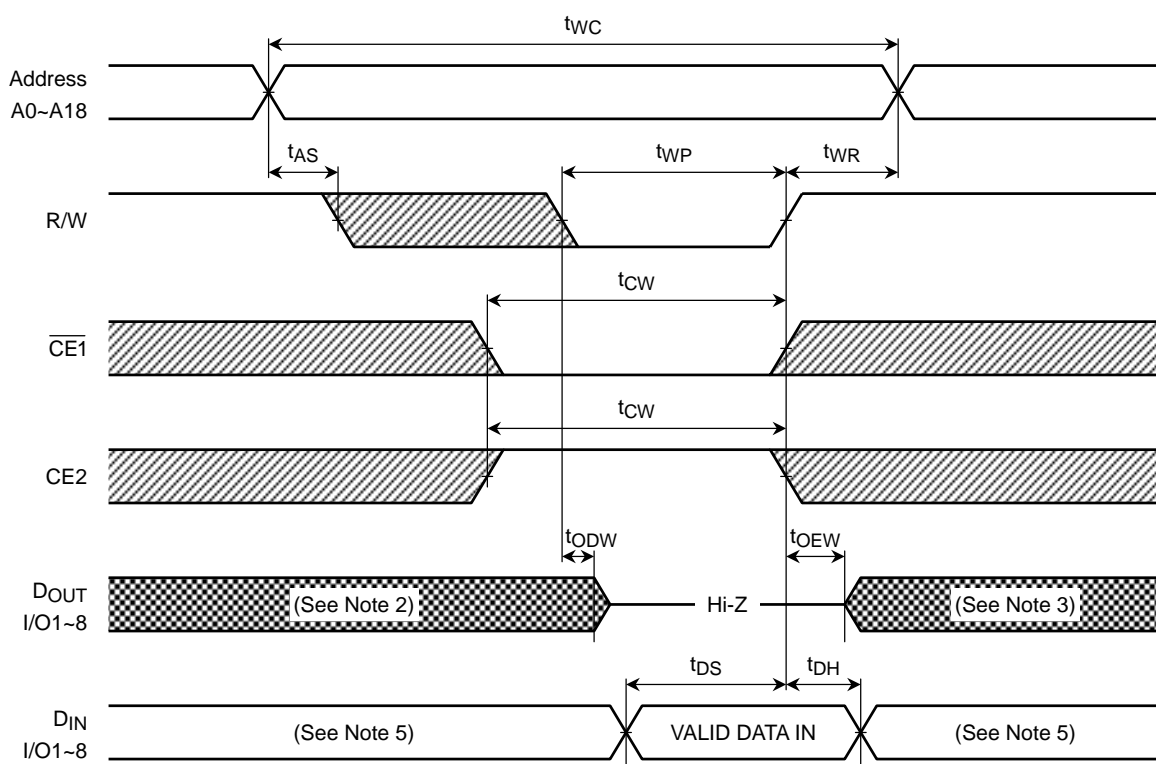


## TIMING DIAGRAMS

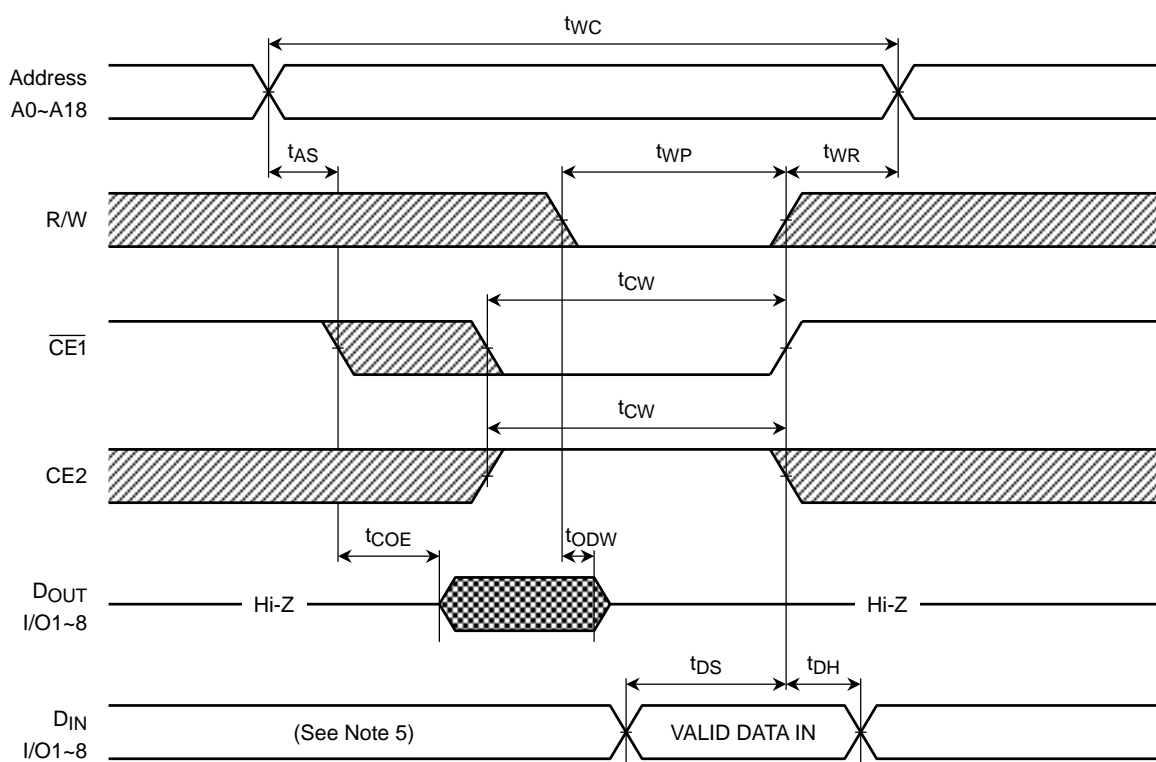
### READ CYCLE (See Note 1)



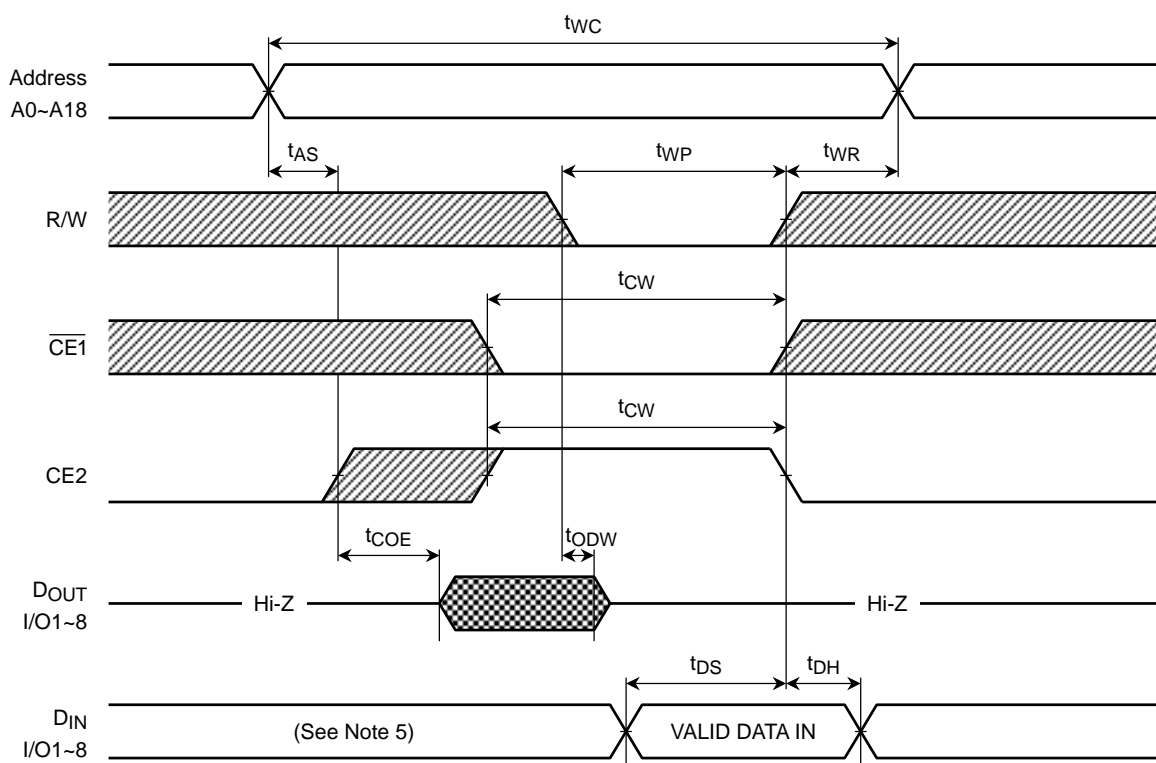
### WRITE CYCLE 1 (R/W CONTROLLED) (See Note 4)



## WRITE CYCLE 2 ( $\overline{\text{CE1}}$ CONTROLLED) (See Note 4)



## WRITE CYCLE 3 (CE2 CONTROLLED) (See Note 4)





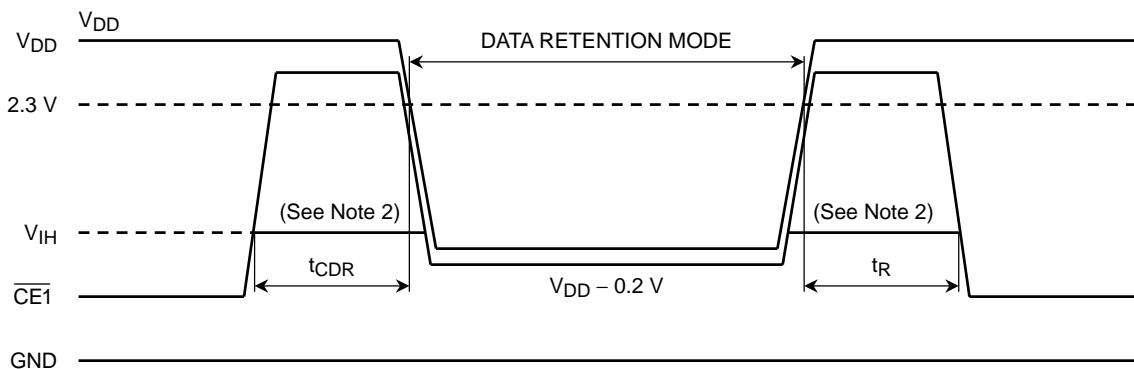
Note:

- (1) R/W remains HIGH for the read cycle.
- (2) If  $\overline{\text{CE1}}$  goes LOW(or CE2 goes HIGH) coincident with or after R/W goes LOW, the outputs will remain at high impedance.
- (3) If  $\overline{\text{CE1}}$  goes HIGH(or CE2 goes LOW) coincident with or before R/W goes HIGH, the outputs will remain at high impedance.
- (4) If  $\overline{\text{OE}}$  is HIGH during the write cycle, the outputs will remain at high impedance.
- (5) Because I/O signals may be in the output state at this time, input signals of reverse polarity must not be applied.

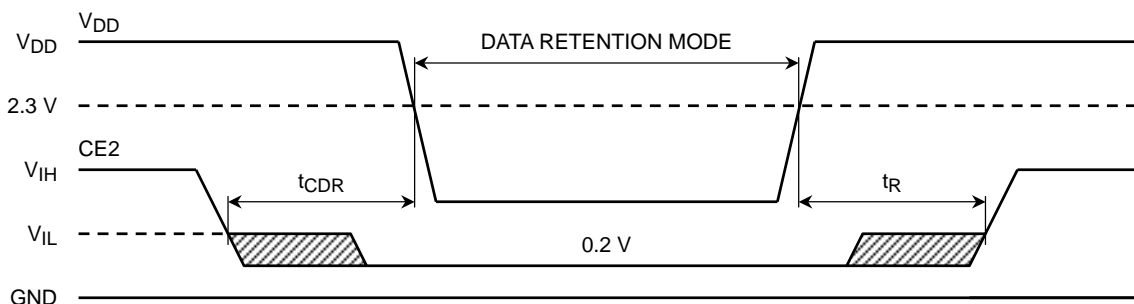
## DATA RETENTION CHARACTERISTICS (Ta = -40° to 85°C)

SYMBOL	PARAMETER		MIN	TYP	MAX	UNIT
$V_{\text{DH}}$	Data Retention Supply Voltage		1.5	—	3.6	V
$I_{\text{DDS2}}$	Standby Current	$V_{\text{DH}} = 3.6 \text{ V}$ Ta = -40~85°C	—	—	10	$\mu\text{A}$
		$V_{\text{DH}} = 3.0 \text{ V}$ Ta = -40~40°C	—	—	2	
		$V_{\text{DH}} = 3.0 \text{ V}$ Ta = -40~85°C	—	—	5	
$t_{\text{CDR}}$	Chip Deselect to Data Retention Mode Time		0	—	—	ns
$t_{\text{R}}$	Recovery Time		5	—	—	ms

### $\overline{\text{CE1}}$ CONTROLLED DATA RETENTION MODE (See Note 1)



### CE2 CONTROLLED DATA RETENTION MODE (See Note 3)



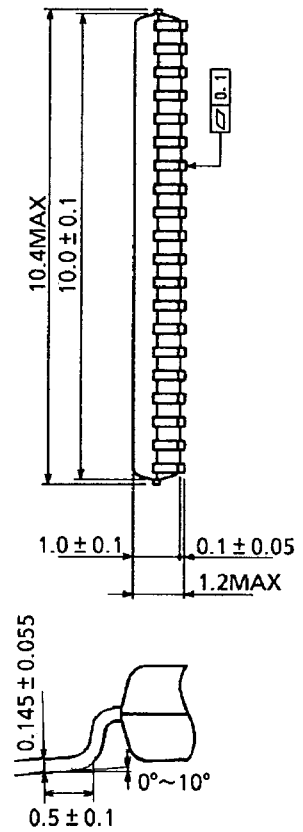
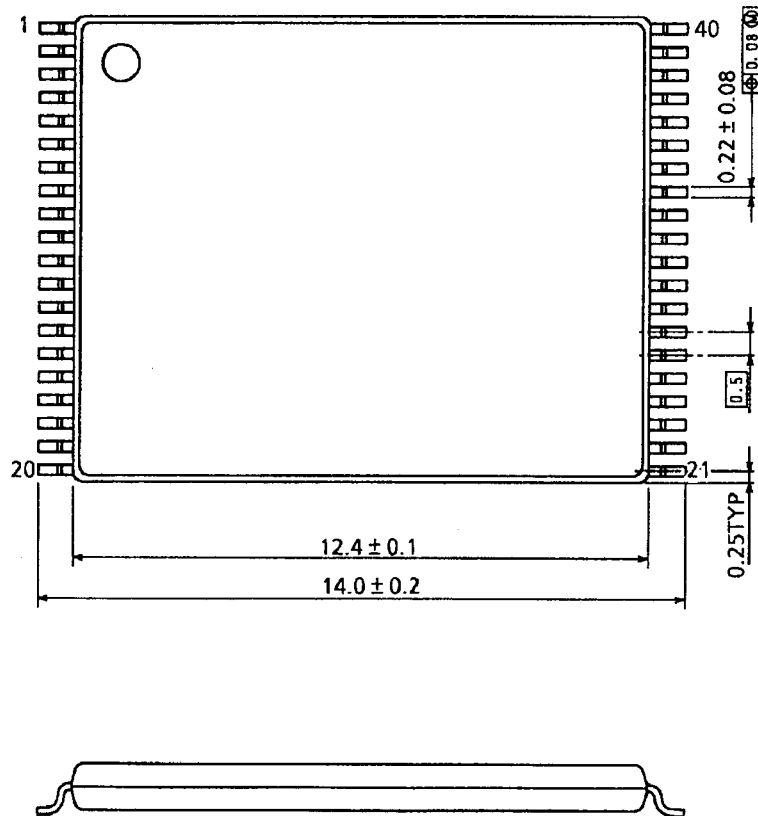
Note:

- (1) In  $\overline{\text{CE1}}$  controlled data retention mode, minimum standby current mode is entered when  $\text{CE2} \leq 0.2 \text{ V}$  or  $\text{CE2} \geq \text{V}_{\text{DD}} - 0.2 \text{ V}$ .
- (2) When  $\overline{\text{CE1}}$  is operating at the  $\text{V}_{\text{IH}}(\text{min.})$  level, the operating current is given by  $\text{I}_{\text{DDS1}}$  during the transition of  $\text{V}_{\text{DD}}$  from 2.3(2.7) to 2.2V(2.4 V).
- (3) In  $\text{CE2}$  controlled data retention mode, minimum standby current mode is entered when  $\text{CE2} \leq 0.2 \text{ V}$ .

## PACKAGE DIMENSIONS

TSOP I 40-P-1014-0.50

Unit : mm



Weight: 0.30 g (typ)

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